

### REMARKS

This application has been reviewed in light of the Office Action dated March 9, 2007. Claims 1, 2, and 7-13 are now presented for examination. Claims 1 and 2 have been amended to define still more clearly what Applicants regard as their invention. Claims 1 and 2 are in independent form. Favorable reconsideration is requested.

The Office Action rejected Claims 1, 2, and 7-10 under 35 U.S.C. § 112, second paragraph, as indefinite.

Without conceding the propriety of these rejections, Claims 1 and 2 have been amended in a manner which obviates both rejections. Accordingly, withdrawal of those rejections is respectfully requested.

Claims 1, 7, and 11-13 were rejected under 35 U.S.C. § 102(e) as being unpatentable over U.S. Patent Application Publication No. 2002/0192935 (Joshi et al.). Claims 2 and 8 were rejected under 35 U.S.C. § 102(e), or alternatively under 35 U.S.C. § 103(a), as being unpatentable over Joshi et al. Claims 9 and 10 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Joshi et al.

Claims 1 and 2 have been amended to even further clarify the claimed subject matter. As amended, Claim 1 recites an image display device, comprising an envelope whose inside is maintained in a reduced pressure atmosphere. The envelope comprises a first substrate, a second substrate opposed to the first substrate, and a frame interposed between the first substrate and the second substrate. The portion of the first substrate opposed to the frame has first areas covered each with a first metal film and

a second area not covered with the first metal film. The first substrate and the frame are seal-bonded with a low melting point metal, with the low melting point metal being brought into contact with the first metal film and the first substrate in the second area. The second area is interposed between the first areas.

Claim 2, as amended, recites an image display device comprising an envelope whose inside is maintained in a reduced pressure atmosphere. The envelope comprises a first substrate, a second substrate opposed to the first substrate, and a frame interposed between the first substrate and the second substrate. The portion of the frame opposed to the first substrate has first areas covered each with a first metal film and a second area not covered with the first metal film. The first substrate and the frame are seal-bonded with a low melting point metal, with the low melting point metal being brought into contact with the first metal film and the frame in the second area. The second area is interposed between the first areas.

Notable features of amended Claim 1 are that a portion of the first substrate opposed to the frame has first areas covered each with a first metal film and a second area not covered with the first metal film, and the second area being interposed between the first areas.

To assist the Examiner in understanding these features, attached is an annotated version of Fig.1. As shown in the attached drawing, there are first areas [1] each covered with a first metal film and second area [2] not covered with the first metal film at a portion of a first substrate (82) opposed to a frame (86), the second area [2] is interposed

between the first areas [1], and a low melting point metal (93) is brought into contact with the first metal film [1] and the first substrate in the second area [2]. Such a constitution (metal films are duplicated (the first areas are positioned so as to sandwich the second area)) makes it possible to realize a novel sealing container which has high airtightness and is unbreakable.

Joshi et al. discloses that the conductive region 12 on the semiconductor substrate 10 and the conductive column 30 (or 31) are connected using the solder joint 35. PbSn and InSb are disclosed as materials of the solder joint 35 (at paragraph [0029]), and a metal such as aluminum, copper, nickel or gold is disclosed as a material of the conductive region 12 (at paragraph [0019]). In addition, Joshi et al. discloses the structure with a part of the conductive region 12 being covered with the passivation layer 14 (Fig. 1(1)). As materials of the passivation layer 14, there are disclosed silicon nitride, glass and polyimide which are different from the material of the conductive region 12.

However, Joshi et al. neither discloses nor suggests that a portion of the first substrate opposed to the frame has first areas covered each with a first metal film and a second area not covered with the first metal film, the second area being interposed between the first areas, as set forth in Claim 1, and a portion of the frame opposed to the first substrate has first areas covered each with a first metal film and a second area not covered with the first metal film, the second area being interposed between the first areas, as set forth in Claim 2. In addition, in Joshi et al., while there is a structure interposed between

the passivation layers 14 made of a nonmetal, there is no area interposed between metal films, as in Claims 1 and 2.

In view of the foregoing, Claims 1 and 2 are believed to be clearly patentable over Joshi et al.

A review of the other art of record has failed to reveal anything which, in Applicants' opinion, would remedy the deficiencies of the art discussed above, as a reference against the independent claims herein. Those claims are therefore believed patentable over the art of record.

The other claims in this application are each dependent from one or another of the independent claims discussed above and are therefore believed patentable for the same reasons. Since each dependent claim is also deemed to define an additional aspect of the invention, however, the individual reconsideration of the patentability of each on its own merits is respectfully requested.

In view of the foregoing amendments and remarks, Applicants respectfully request favorable reconsideration and early passage to issue of the present application.

Applicants' undersigned attorney may be reached in our New York office by telephone at (212) 218-2100. All correspondence should continue to be directed to our below listed address.

Respectfully submitted,

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